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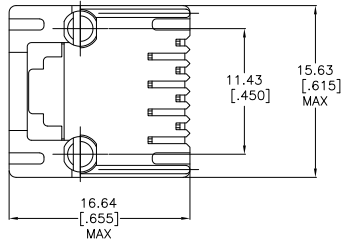
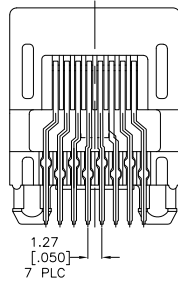
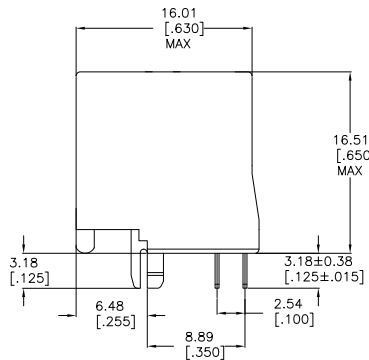
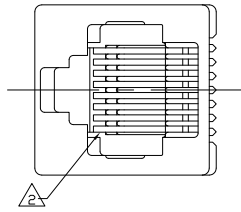
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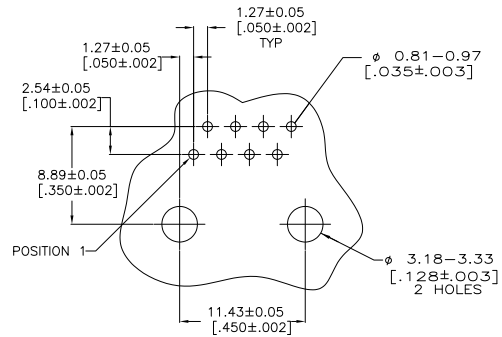
LOC	DIST	REVISIONS				
AA	00	F	LNK	DATE	MIN	APD
		B	ECO-07-017784	14AUG07	LAM	PR



1. MATERIAL: HOUSING - HTN MOLDING COMPOUND, UL 94V-0 COLOR: BLACK  
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27μm [.000050] MIN THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA, 3.81μm [.000150] MIN THICK MATTE TIN IN SOLDER AREA AND 1.27μm [.000050] MIN THICK NICKEL UNDERPLATE

△ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81 PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

3. BULK PACKAGED IN A TRAY.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
 COMPONENT SIDE

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRN L. MAYER	ORJAN2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK S. REEDCE	14AUG2007	NAME S. FLICKINGER	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		ZPFC 14AUG2007		MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS	
0 PLC ± -		PRODUCT SPEC 108-1163		SIZE A2	
1 PLC ± -		APPLICATION SPEC 114-2048		CAGE CODE 00779	
2 PLC ± 0.1% (0.05)		WEIGHT -		DRAWING NO C=5569284	
3 PLC ± -		MATERIAL -		RESTRICTED TO -	
4 PLC ± -		FINISH -		SCALE 4:1	
ANGLES ± -		SEE NOTE 1		SHEET 1 of 1	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		REV B	
		CUSTOMER DRAWING			

AMP 1471-9 REV 31MMR2000

5569284

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